

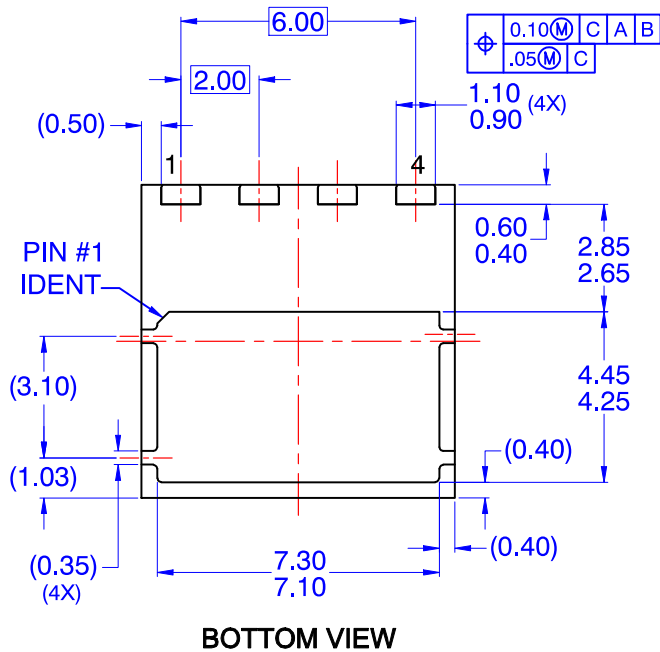
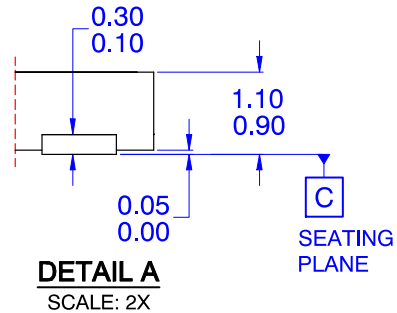
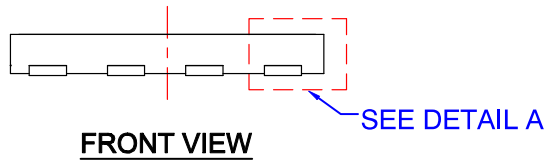
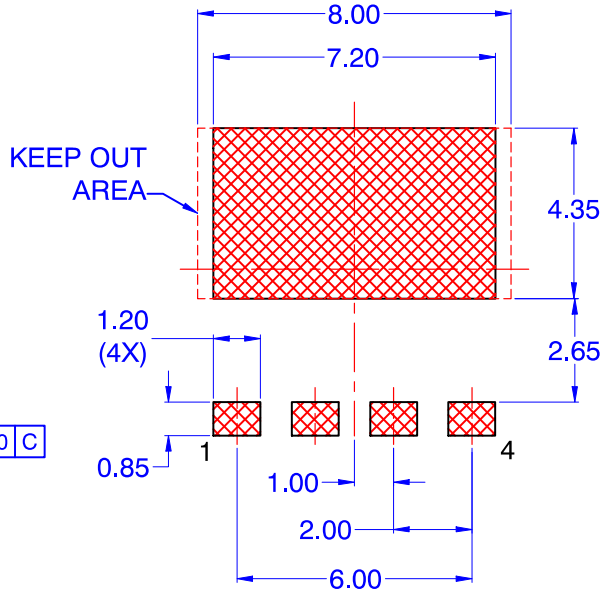
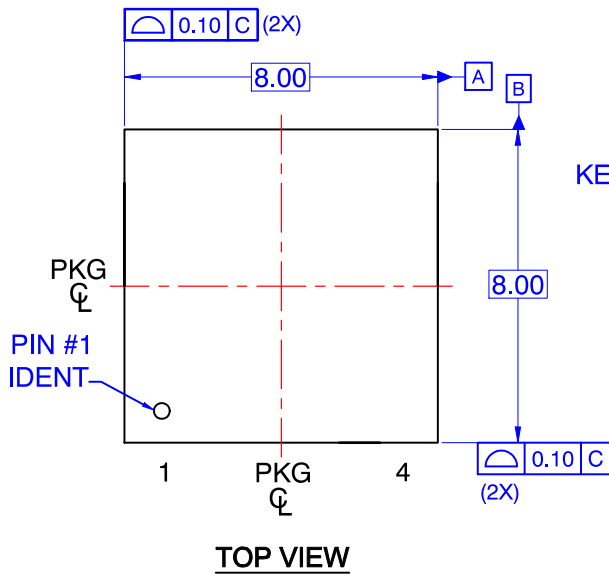
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



PQFN4 8X8, 2P
CASE 483AP
ISSUE O

DATE 30 SEP 2016



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 B) DIMENSIONS ARE INCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR PROTRUSIONS.
 C) ALL DIMENSIONS ARE IN MILLIMETERS.
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